HUITIAN

Technical Data Sheet

5272

Two-component thermal conductive silicone gel

Product description

- Two-component room temperature curing silicone gel
- 1:1 heat curing

Product features

- High thermal conductivity
- Excellent insulation properties
- Good weather and aging resistance
- Flame retardant grade: up to UL94V-0
- Working temperature: -40°C~200°C
- RoHS Directive

Typical applications

Heat dissipation in NEV battery cells and modules; applications with heat dissipation requirements such as heat sinks for electronic components, flip chips, transformers, and high-power LEDs

Directions for use

Before mixing: Clean the dispensing surface, and remove oil and other impurities.

Mixing and dispensing: Mix as per a weight ratio of 1:1. Squeeze out the glue and fit it to the surface.

Curing: Both room temperature curing and heat curing are acceptable. The curing speed of the glue has a great relationship with the curing temperature. The higher the temperature, the faster the curing.

Storage

Store at 8-28°C in a cool and dry place.

Shelf life is 6 months.

Packing specification

Order code: 527204 350ml/cartridge

5272A6 25 kg/barrel

5272B6 25 kg/barrel

Technical parameters

Reference standard	Item	Unit	Value
Properties before curing (25±2°C, 60±5%RH)			
Q/HTXC 2	Appearance (A)	--	White paste
	Appearance (B)	--	Blue paste
GB/T 2794	Viscosity (A)	Pa·s	80-160
	Viscosity (B)	Pa·s	80-160
GB/T13354	Density (A)	g/cm^3	2.8±0.1
	Density (B)	g/cm^3	2.8±0.1
Curing properties (A:B=1:1)			
Q/HTXC 2	Curing time (80°C)	min	30
Q/HTXC 2	Initial curing time (25°C)	min	240
Properties after curing (25±2°C, 60±5%RH)			
GB/T531	Hardness	Shore 00	40~60
ASTM D149	Dielectric strength	KV/mm	7
ASTM D150	Dielectric constant	/	5
ISO 22007	Thermal conductivity	W/m·K	2.5±10%
US EPA8270E	D3-D10	Ppm	＜1,000

Note: The reference standards are not dated and their latest versions are applicable to this document.

Cautions

This product is non-hazardous, but should never be exposed to mouth and eyes.

The glue should be stored in a sealed container. Use up the mixed glue at once to avoid waste.

The glue will not cure if exposed to a certain amount of the following chemicals:

- Organic compounds of N, P and S;
- Ionic compounds of Sn, Pb, Hg, As, etc.;
- Compounds containing alkyne and polyvinyl.

To avoid the above problem, try to wipe off the residual rosin and flux when using the glue on the circuit board, and use soldering tin with low lead content.

Please consult the MSDS of the product for safety information.

Note:
The data in this document were obtained under laboratory conditions. Due to differences in the operating environment, the user can refer to these data and operating conditions for analysis and testing. Huitian does not guarantee the sale of products or the use of the products under specific working conditions and does not accept any liability for direct, indirect or incidental damage. If users encounter any problems in the process of use, please contact the technical service department of Huitian New Material and all assistance will be provided.

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